

Product Declaration

Date : June 19, 2025

Applicant: Hyundai Mobis Co., Ltd.

Product Type: Car Infotainment system

Basic Model: DA651ZZZGG

Additional Models: DA653ZZZGG, DA654ZZZGG, DA656ZZZGG

We, Hyundai Mobis Co., Ltd., provide the product information.

1. The Difference between Basic Model and Additional Model

Model		BT/WLAN	CCS IC	RVM Camera	SVM Camera
Basic model	DA651ZZZGG	O	O	O	X
Variant model	DA653ZZZGG	O	X	O	X
	DA654ZZZGG	O	X	X	O
	DA656ZZZGG	O	X	X	X

2. The CCS IC functions as a digital interface for data communication with other devices.

3. Please refer to the Annex for detail difference.

If you have any questions regarding the difference, please contact us.

Sincerely,

Signed by:



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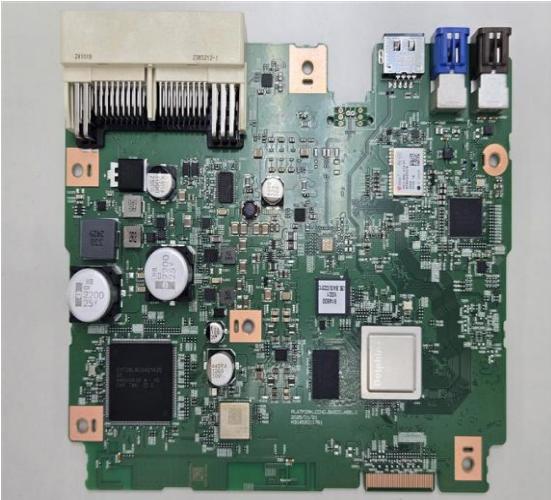
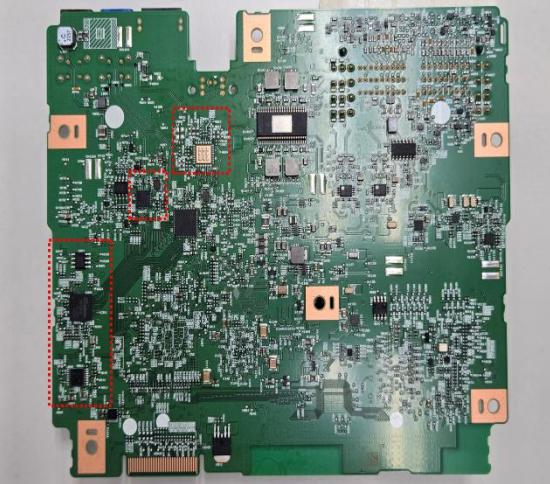
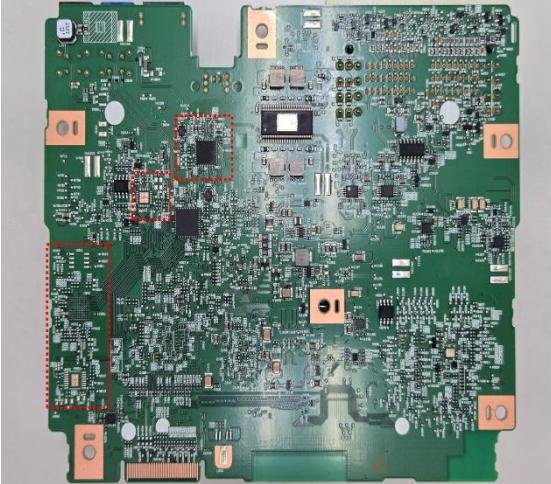
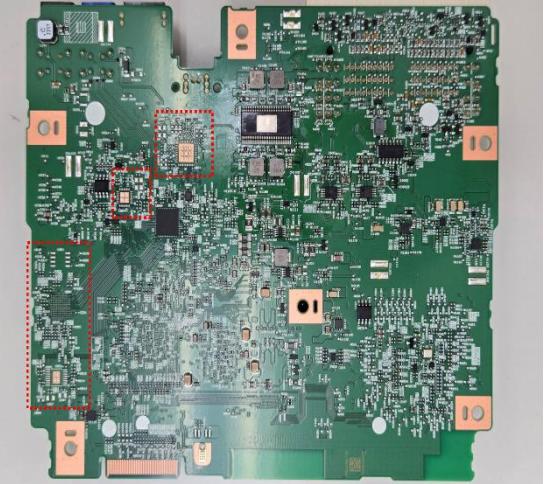
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Place : South Korea

[Annex I] Difference between SVM, RVM, and no camera

RVM	SVM	No camera
 A photograph of a green printed circuit board (PCB) for a RVM (Reference Validation Model) system. The board is densely populated with components, including a central processor, memory chips, and various connectors. Several orange and white heat sinks are attached to the board, notably on the left side and near the top center. The board is mounted on a light-colored plastic frame.	 A photograph of a green printed circuit board (PCB) for an SVM (Software Validation Model) system. The layout is very similar to the RVM board, featuring a central processor, memory chips, and various connectors. Orange and white heat sinks are also present, including a prominent one on the left side and another near the top center. The board is mounted on a light-colored plastic frame.	 A photograph of a green printed circuit board (PCB) for a system without a camera. The board is densely populated with components, including a central processor, memory chips, and various connectors. Orange and white heat sinks are attached to the board, notably on the left side and near the top center. The board is mounted on a light-colored plastic frame.
 A photograph of the underside of the RVM motherboard. The board is green and shows various components and connectors. Two specific areas are highlighted with red dashed boxes: one on the left side and another on the right side. These boxes likely indicate the locations of the camera components that are present in the RVM model but absent in the SVM and 'no camera' models.	 A photograph of the underside of the SVM motherboard. The board is green and shows various components and connectors. Two specific areas are highlighted with red dashed boxes: one on the left side and another on the right side. These boxes likely indicate the locations of the camera components that are present in the SVM model but absent in the RVM and 'no camera' models.	 A photograph of the underside of the 'no camera' motherboard. The board is green and shows various components and connectors. Two specific areas are highlighted with red dashed boxes: one on the left side and another on the right side. These boxes likely indicate the locations where camera components would be present in the RVM and SVM models but are absent in this 'no camera' model.

[Annex II] Difference between CCS IC specification and non-CCS IC specification.

CCS IC specification	Non-CCS IC specification
	